



<b>Form Type</b>	Distribute	<b>Version</b>	2.0	<b>Ref</b>	IPC 1752A	<b>Sectionals</b>	Material Info	<b>Subsectionals</b>	D, A
<b>Supplier Information</b>									
<b>Company Name</b>	TE Connectivity	<b>Request Document ID</b>		<b>Contact Name</b>	Benfer David W	<b>Contact Title</b>	Product Compliance Engineer for DND		
<b>Company Unique ID</b>	TE Connectivity	<b>Response Date</b>	2018-05-04	<b>Contact Email</b>	dave.benfer@te.com				
<b>Contact Phone Number</b>	717-986-3725								
<b>Legal Statement</b>									
<b>Supplier Acceptance</b>	true								
<b>Legal Statement</b>									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
<b>Product</b>									
<b>Manufacturer Item number</b>	1-1775210-1	<b>Amount</b>	27400.0	<b>Version</b>	-	<b>Identity</b>			
<b>Manufacturer Item Name</b>	D-SUB 5.08mm,9 POS PLUG OVER 15 POS RCPT	<b>Weight Uom</b>	mg	<b>Mfr Site</b>		<b>Authority</b>			
<b>Date</b>		<b>UOM</b>	Each						
<b>EUROHS-0508</b>	Product(s) meets EU RoHS requirements by application of the selected exemption(s)								
<b>ChinaRoHS-0508</b>	Product(s) is NOT eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products								
<b>EUREACH-0117</b>	REACH Candidate Substances of Very High Concern ARE NOT Yet Reviewed								
<b>Complex Article Description</b>	REACH Candidate Substances of Very High Concern according to Once an Article Always an Article are Not Yet Reviewed								
<b>Product Disclosure</b>									
<b>Sub-Item/Material/Substance</b>	<b>Level</b>	<b>Name</b>	<b>Substance Category</b>	<b>Substance CAS</b>	<b>Substance Concentration</b>	<b>Quantity</b>	<b>Mass per Unit</b>	<b>UOM</b>	<b>Exemption</b>
Material	1	Boardlock - Tin Plating				1.0	0.08	mg	
Substance	2	Tin	Supplier	7440-31-5	99.9	1.0	0.07992	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.1	1.0	8.0E-5	mg	
Material	1	Shell				1.0	9295.0	mg	
Substance	2	Silicon	Supplier	7440-21-3	11.0	1.0	1022.45	mg	
Substance	2	Manganese	Supplier	7439-96-5	23.0	1.0	2137.85	mg	
Substance	2	Carbon	Supplier	7440-44-0	3.0	1.0	278.85	mg	
Substance	2	Sulfur, homopolymer	Supplier	9035-99-8	1.0	1.0	92.95	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	18.0	1.0	1673.1	mg	
Substance	2	Aluminum	Supplier	7429-90-5	44.0	1.0	4089.8	mg	
Material	1	Boardlock				1.0	2240.0	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	1.52E-5	1.0	3.4048E-4	mg	
Substance	2	Zinc	Supplier	7440-66-6	34.6	1.0	775.04	mg	
Substance	2	Iron	Supplier	7439-89-6	0.0199848	1.0	0.44766	mg	
Substance	2	Copper	Supplier	7440-50-8	65.38	1.0	1464.512	mg	
Material	1	Contact - Tin Plating				1.0	0.112	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.1	1.0	1.12E-4	mg	
Substance	2	Tin	Supplier	7440-31-5	99.9	1.0	0.11189	mg	
Material	1	Housing				1.0	8003.0	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	3.0	1.0	240.09	mg	
Substance	2	Glass, oxide, chemicals	Supplier	65997-17-3	29.25	1.0	2340.8775	mg	

Substance	2	Poly[imino(1,6-dioxo-1,6-hexanediy)imino-1,6-hexanediy]	Supplier	32131-17-2	62.15	1.0	4973.8645	mg	
Substance	2	Carbon black	Supplier	1333-86-4	0.3	1.0	24.009	mg	
Substance	2	Sulfurous acid, sodium salt (1:1), polymer with formaldehyde and 1,3,5-triazine-2,4,6-triamine	Supplier	64787-97-9	5.3	1.0	424.159	mg	
Material	1	Screw - Nickel Plating				1.0	0.601	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	0.598	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.5	1.0	0.003005	mg	
Material	1	Contact - Nickel Plating				1.0	0.204	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.5	1.0	0.00102	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	0.20298	mg	
Material	1	Boardlock - Nickel Plating				1.0	0.05	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	0.04975	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.5	1.0	2.5E-4	mg	
Material	1	Contact - Gold Plating				1.0	0.105	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.3	1.0	3.15E-4	mg	
Substance	2	Gold	Supplier	7440-57-5	99.7	1.0	0.10469	mg	
Material	1	Shell - Nickel Plating				1.0	0.848	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	0.84376	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.5	1.0	0.00424	mg	
Material	1	Screw				1.0	1660.0	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	1.92	1.0	31.872	mg	6(c) Lead as an alloying element in copper containing up to 4% lead by weight
Substance	2	Copper	Supplier	7440-50-8	57.6	1.0	956.16	mg	
Substance	2	Zinc	Supplier	7440-66-6	40.11	1.0	665.826	mg	
Substance	2	Iron	Supplier	7439-89-6	0.37	1.0	6.142	mg	
Material	1	Contact				1.0	6200.0	mg	
Substance	2	Zinc	Supplier	7440-66-6	34.6	1.0	2145.2	mg	
Substance	2	Iron	Supplier	7439-89-6	0.0199848	1.0	1.23906	mg	
Substance	2	Copper	Supplier	7440-50-8	65.38	1.0	4053.56	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	1.52E-5	1.0	9.424E-4	mg	